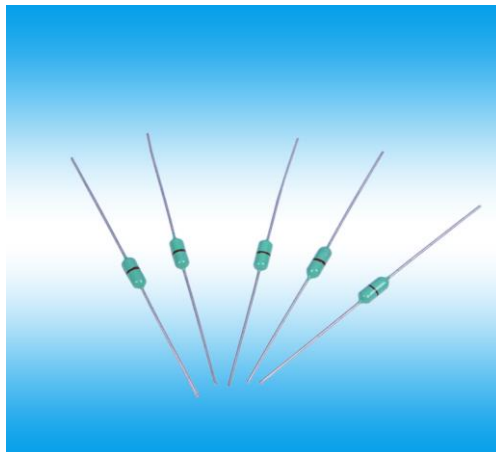


Type MGC/Fast Acting Micro Fuse

MGC系列/快断微型保险丝



Description

- Axial Leaded Fast Acting Thru-Hole Fuse
快断引线型保险丝
- Tin-lead Plated Copper Lead Wires
镀锡铜线
- High Temperature Epoxy Plastic Body
高温环氧树脂

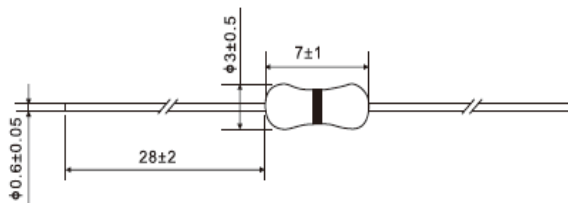
Features 产品特点

- Meets the requirements of UL248-14
符合UL248-14的要求
- Single Pigtail Axial Lead format
单帽轴向引线
- Fast Acting, ceramic body fuse in a compact package
快断，小型陶瓷熔断体
- Pb-free, RoHS compliant
Pb-free, 通过无铅认证
- Available in ratings of 250mA to 10Amperes
可在额定250mA到10A

Applications 产品应用

- Lighting system
照明系统
- Office automation machines
办公自动化机器
- Audio/Video system Medical equipment
音频/视频系统医疗设备
- Power supply
电源供应器
- LCD/PDP TV
液晶/PDP电视
- LCD monitor
液晶显示器

Dimensions (Unit:mm) 尺寸 (单位: mm)



Electrical Characteristics 熔断特性

Electrical Characteristics 熔断特性		
Ampere Rating	% of Amp Rating	Opening Time
250mA-10A	100%	4 Hours Minimum
	200%	5 Seconds Maximum

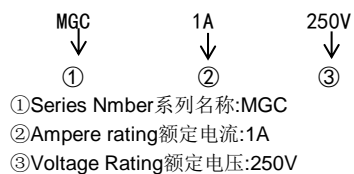
Type MGC/Fast Acting Micro Fuse

Electrical Specifications 电气特性

Catalog Number	Ampere Rated In	Voltage Rating(V) Interrupting Rating (A)	Norminal Resistance Cold(Ohm)	Norminal Melting $I^2T(A^2sec)$
MGC250mA	250mA	50A@125V/250VAC	0.2920	0.008
MGC375mA	375mA		0.1850	0.012
MGC500mA	500mA		0.1460	0.150
MGC750mA	750mA		0.0695	0.11
MGC1A	1A		0.0640	0.10
MGC1.5A	1.5A		0.0400	0.250
MGC2A	2A		0.0340	0.80
MGC2.5A	2.5A		0.0270	1.25
MGC3A	3A		0.0310	0.90
MGC3.5A	3.5A		0.0200	1.20
MGC4A	4A		0.0170	4.80
MGC5A	5A		0.0140	5
MGC7A	7A		0.0150	7
MGC10A	10A		0.0070	21

Packaging and Type Designation 包装和型号名称

Formation of Type Designation 类型命名的形成

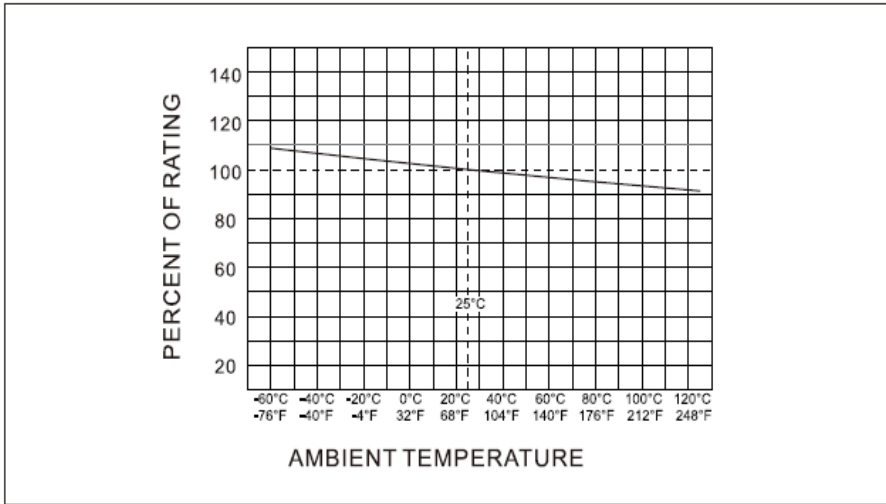


Packaging 包装

On Tape: MGC-2000pcs Per Reel, 10000pcs Outer Box

Type MGC/Fast Acting Micro Fuse

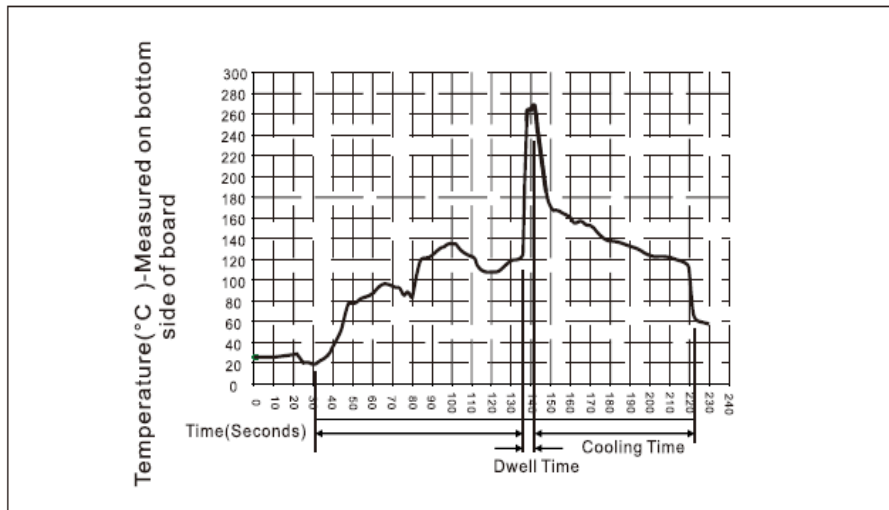
Temperature Rerating Curve 额定温度曲线



Note:

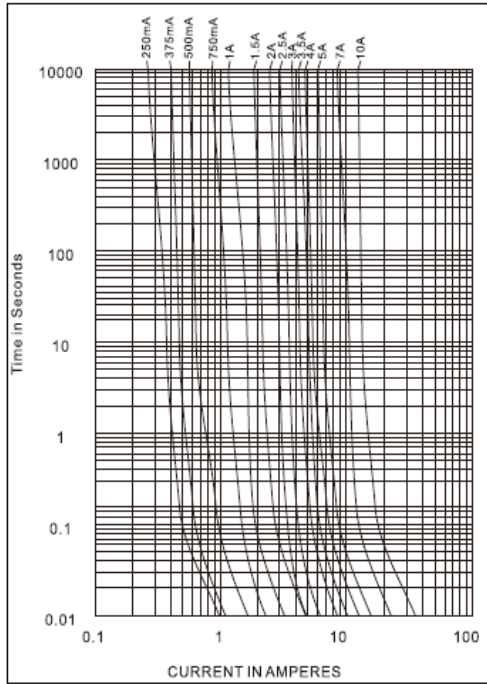
Derating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Soldering Parameters-Wave Soldering 焊接参数



Type MGC/Fast Acting Micro Fuse

Time-Current Characteristics熔断时间特性表



Operation Temperature工作温度

→ -40°C to 125°C

Physical Specification Materials规格材料

- Ceramic Body
- Nickel Plated Brass Caps
- Lead Wire: Tin plated Copper, Diameter 0.6 mm

Recommended Process Parameters工艺参数

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

→ Recommended Hand-Solder Parameters:

-Solder Iron Temperature: 350°C +/- 5°C

-Heating Time: 5 seconds max.

-Note: These devices are not recommended for IR or Convection Reflow process